

C1206C683K1RACTM

Aliases (C1206C683K1RAC7025) SMD Comm X7R, Ceramic, 0.068 uF, 10%, 100 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	Yes
AEC-Q200	No
Typical Component Weight	17 mg
Shelf Life	78 Weeks
MSL	1

		Specifications	
	1206	Capacitance	0.068
	3.2mm +/-0.2mm	Measurement Condition	1 kHz 1.
	1.6mm +/-0.2mm	Tolerance	10%
	0.78mm +/-0.10mm	Voltage DC	100 VD
	1.5mm MIN	Dielectric Withstanding Voltage	250 VE
	0.5mm +/-0.25mm	Temperature Range	-55/+12
		Temp. Coefficient	X7R
s		Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kl
	T&R, 180mm, Plastic Tape		
	4000		

Dimensions Chip Size L W т s в

Packaging Specifications Ρ

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Capacitance	0.068 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5%1kHz1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	14.7059 GOhms

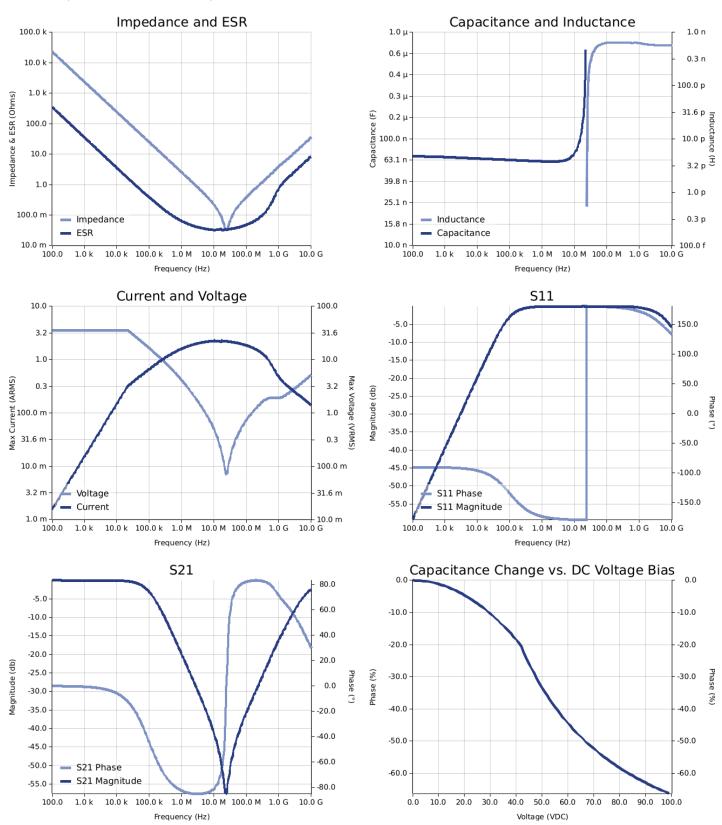
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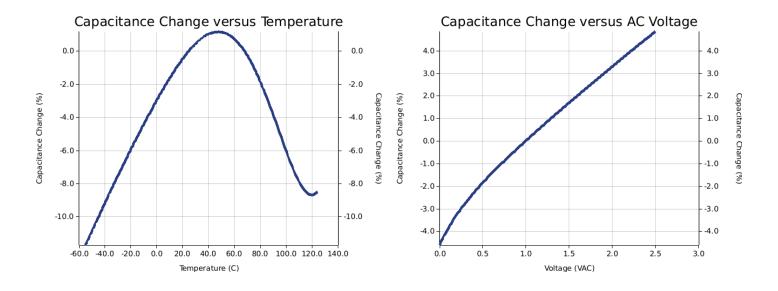
Simulations

For the complete simulation environment please visit K-SIM.





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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.